FINAL PRODUCT/PROCESS CHANGE NOTIFICATION # 16752

Generic Copy

Issue Date: 25-Jan-2012

TITLE: Bottom mark elimination for SOIC devices Atp1

PROPOSED FIRST SHIP DATE: 25-Apr-2012

AFFECTED CHANGE CATEGORY(S): Marking process – bottom mark process

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or <Joh.Villanueva@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office

ADDITIONAL RELIABILITY DATA: Available
Contact your local ON Semiconductor Sales Office or <Phine.Guevarra@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

To improve cycle time, bottom mark is eliminated for SOIC packages on specific devices.

RELIABILITY DATA SUMMARY: Not applicable

ELECTRICAL CHARACTERISTIC SUMMARY: Not applicable

CHANGED PART IDENTIFICATION: No change

List of affected General Parts:

AMIS41683CANN1G
AMIS41683CANN1RG

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Marking Samples:

MARKING LAYOUT:

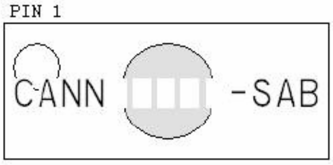
Existing **Proposed**

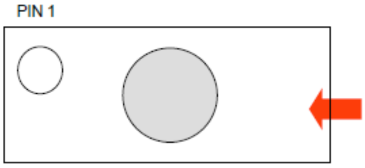
TOP

Transfer device on Top package

Ld Type: SODM 14
Device: OCANN-001-ASY

BOTTOM





Removed device